



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



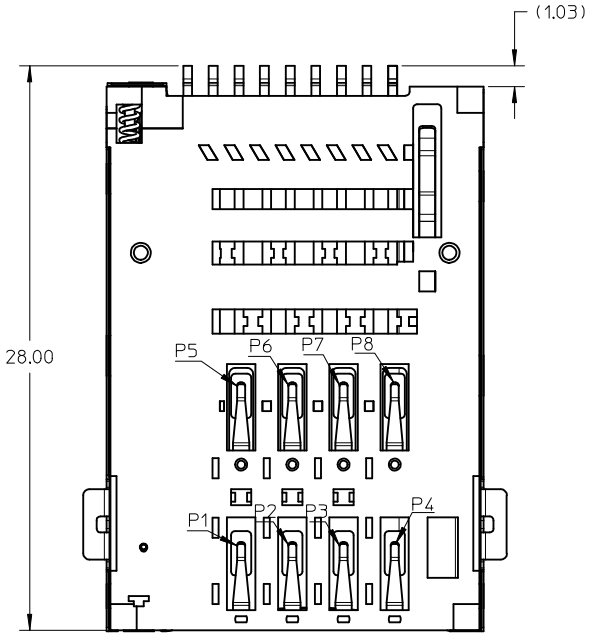
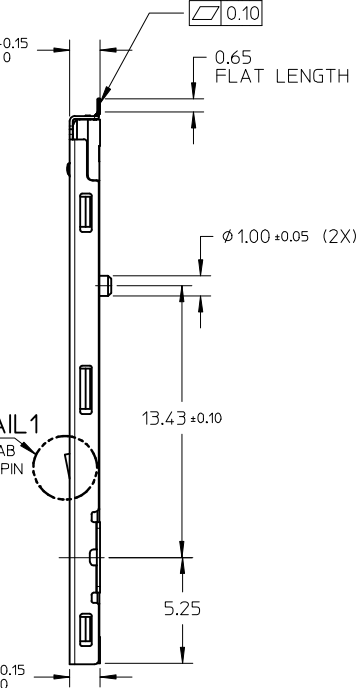
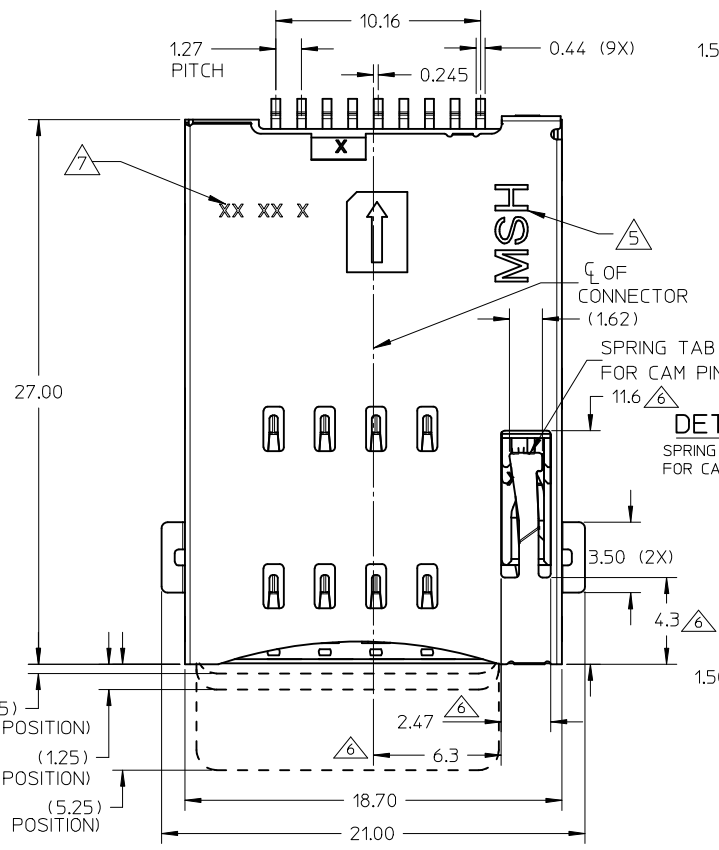
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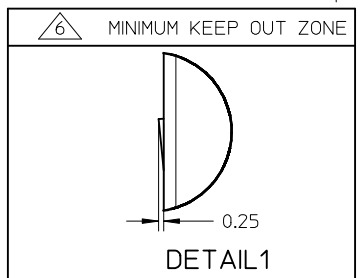




(0.45)
(CARD POSHED POSITION)
(1.25)
(CARD LOCKED POSITION)
(5.25)
(CARD EJECTED POSITION)

- NOTES:
1. MATERIALS: HOUSING, CAM, DUMMY CARD: HIGH TEMP THERMOPLASTIC, UL94V-0, BLACK
TERMINAL, DETECT PIN: COPPER ALLOY
METAL SHELL, COIL SPRING, CAM PIN: STAINLESS STEEL
 2. FINISHES: 0.76µm MIN GOLD ON CONTACT AREA OVER 1.27µm NICKEL UNDERPLATE.
2.54µm MIN MATTE TIN ON SOLDER TAIL AREA OVER 1.27µm NICKEL UNDERPLATE.
GOLD FLASH ON SHELL SOLDER TAB OVER 1.27µm NICKEL UNDERPLATE.
 3. PRODUCT SPECIFICATION: PS-78526-001
 4. PACKAGING SPECIFICATION: PK-78526-001
 5. MOLEX LOGO LOCATED APPROXIMATELY AS SHOWN.
- △ MINIMUM KEEP OUT ZONE FROM TOP SURFACE OF SHELL DURING INSERTION AND WITHDRAWAL OF SIM CARD
▽ DATE CODE PRINTING: XX XX X
DAY
WEEK
YEAR

HALOGEN FREE



785260011	W/O DUMMY CARD
785260001	WIHT DUMMY CARD
ASSEMBLY P/N.	DESCRIPTION

ADD NEW P/N	DESCRIPTION
EC NO: S2012-0960	
DRWN: JZENG	2012/07/31
CHKD: JTAN02	2012/08/27
APPR: KHL JM	2012/09/05
A8	

QUALITY SYMBOLS	DESCRIPTION
▽ _A =0	
▽ _E =0	
▽ _P =0	

GENERAL TOLERANCES (UNLESS SPECIFIED)	mm	INCH
	4 PLACES ± ---	± ---
ANGULAR ± 3 °	3 PLACES ± ---	± ---
	2 PLACES ± 0.25	± ---
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	1 PLACE ± ---	± ---
	SEE TABLE	

DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
MM ONLY		NTS	METRIC	
DRAWN BY	DATE	TITLE		
CGOH	2009/07/17	SIM CARD CONNECTOR		
CHECKED BY	DATE	PUSH PUSH TYPE		
JTAN02	2009/08/17	HEIGHT 1.5MM		
APPROVED BY	DATE	MOLEX INCORPORATED		
BOKOK	2010/11/11	MOLEX INCORPORATED		
MATERIAL NO.	DOCUMENT NO.	SHEET NO.		
		SD-78526-001		
SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
A3				

10 9 8 7 6 5 4 3 2 1

F

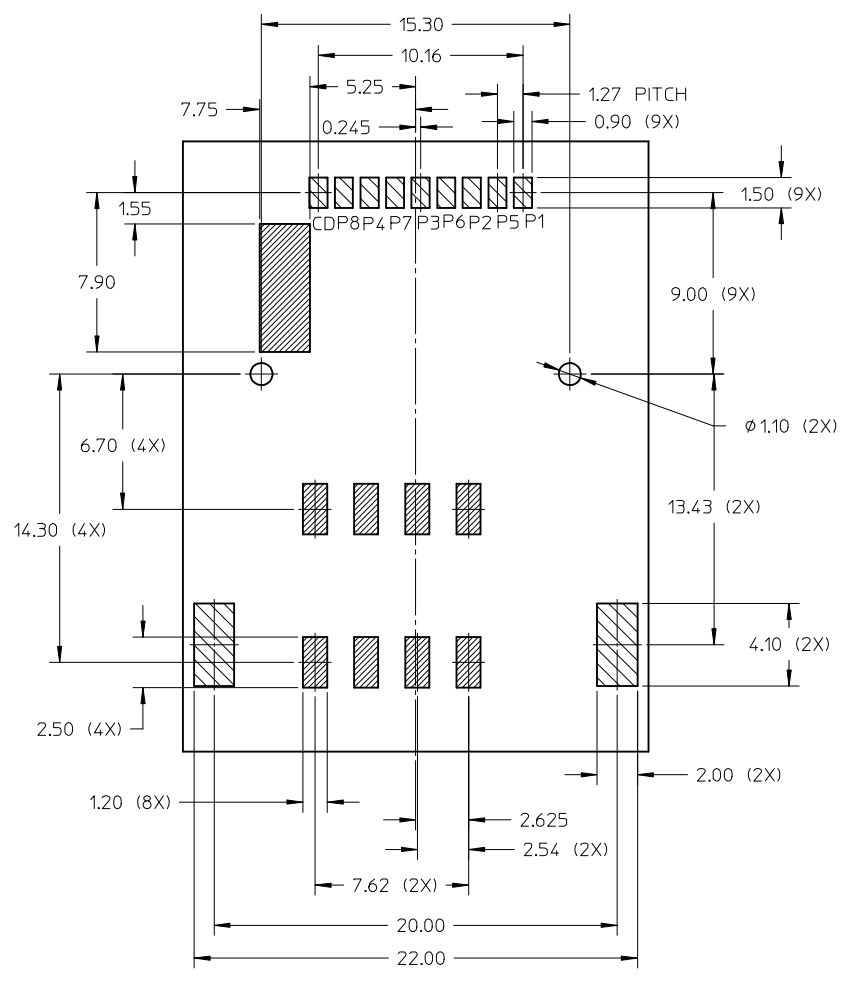
E

D

C

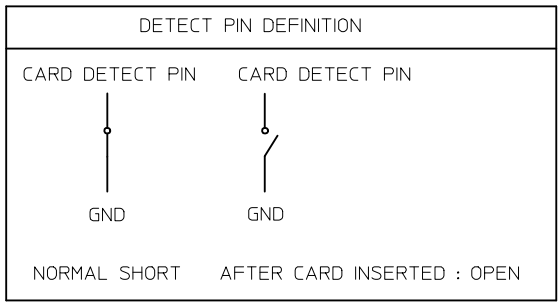
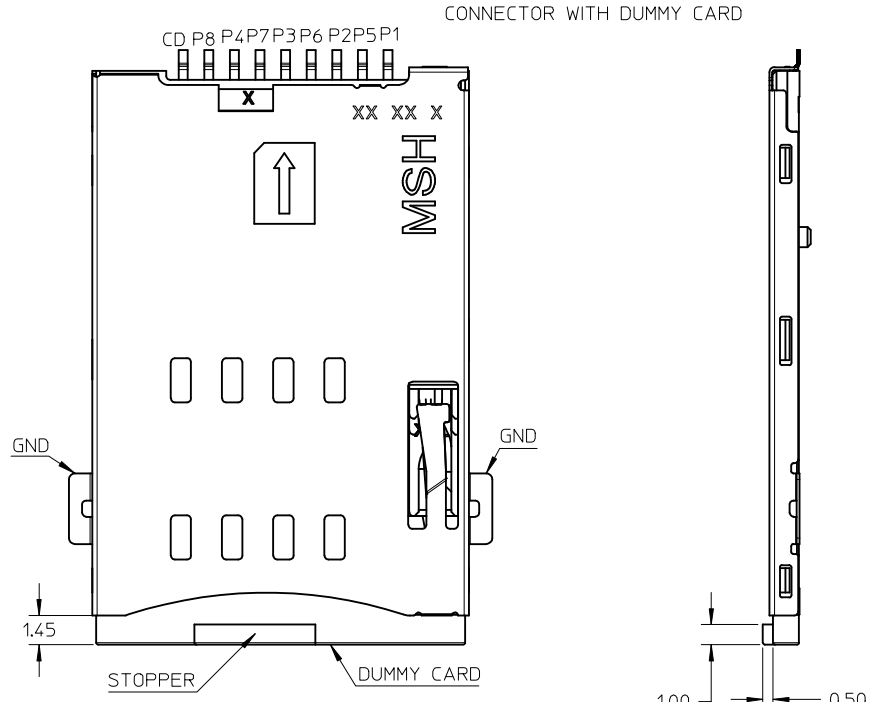
B

A



RECOMMENDED PCB LAYOUT FOR 78526 SERIES
(GENERAL TOLERANCE+0.05)

- CIRCUIT TRACE KEEP OUT AREA
- SOLDERING PAD AREA

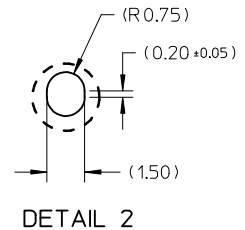
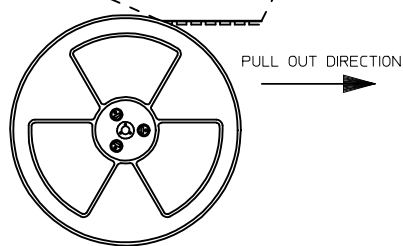
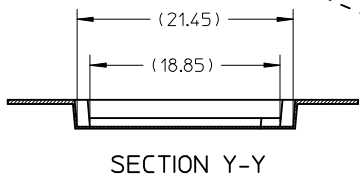
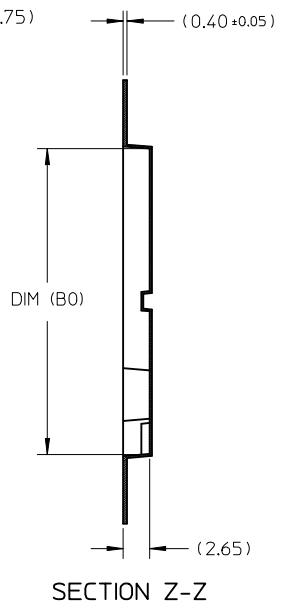
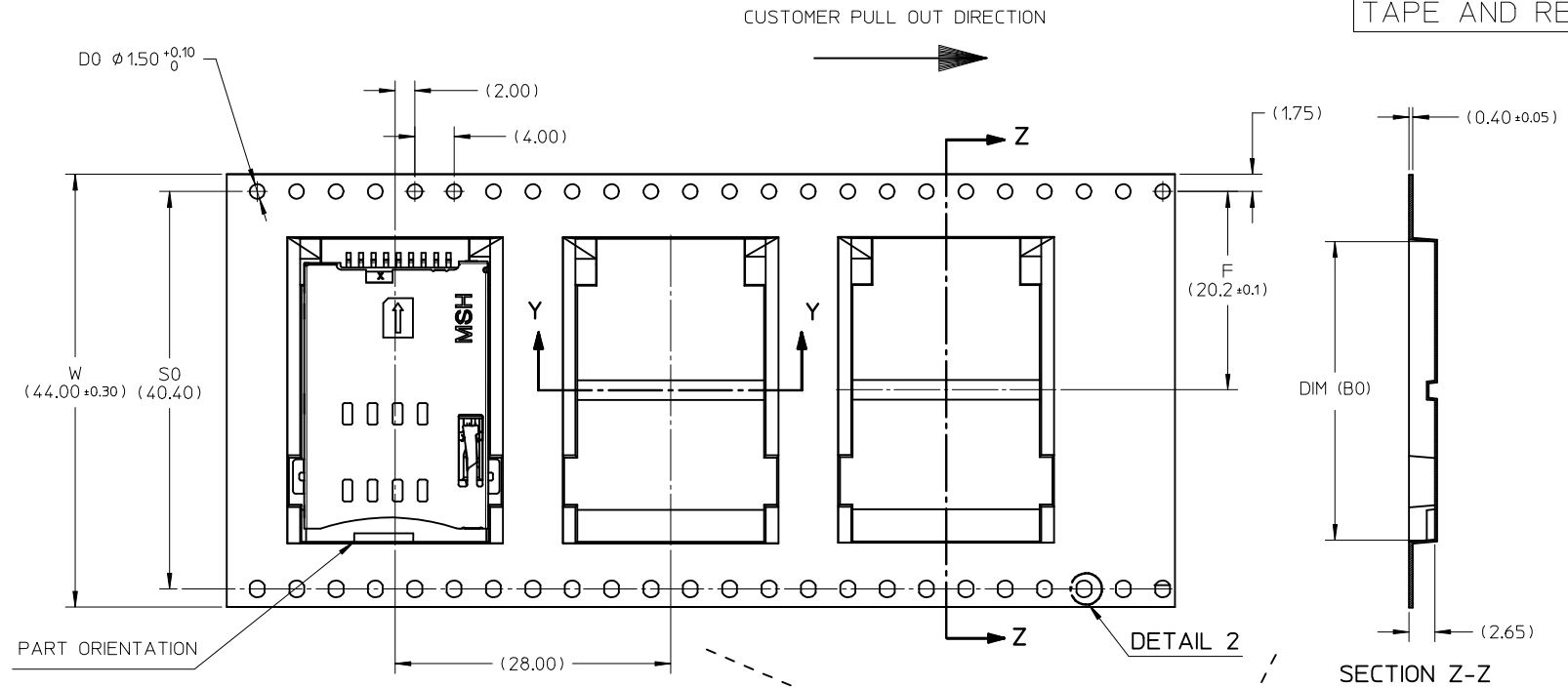


SEE SHEET 1 EC NO: S2012-0960 DRWN: JZENG CHKD: JTAN02 APPR: KHL JM	2012/07/31 2012/08/27 2012/09/05	DESCRIPTION QUALITY SYMBOLS $F_A=0$ $F_G=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
				mm	INCH	DRAWN BY CGOH	DATE 2009/07/17	TITLE	SIM CARD CONNECTOR PUSH PUSH TYPE HEIGHT 1.5MM		
				4 PLACES ± ---	± ---	CHECKED BY JTAN02	DATE 2009/08/17				
				3 PLACES ± ---	± ---	APPROVED BY BOKOK	DATE 2010/11/11				
	2 PLACES ± 0.25	± ---	ANGULAR ± 3 °		MATERIAL NO.	DOCUMENT NO.		SHEET NO.			
	1 PLACE ± ---	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1		MOLEX INCORPORATED		2 OF 3		
A8					SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

9 8 7 6 5 4 3 2 1

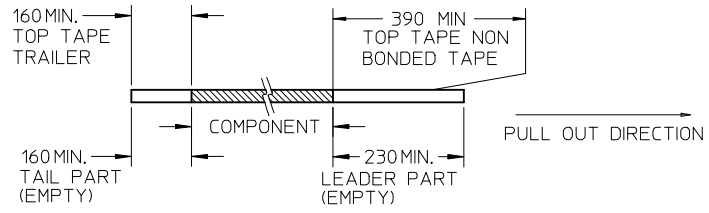
10 9 8 7 6 5 4 3 2 1

TAPE AND REEL PACKING

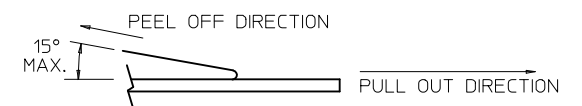


NOTES:

1. LEADER AND TRAILER TAPE



2. PEELING OFF FORCE OF THE TOP TAPE: 10 - 130gf. (PEELING DIRECTION AS SHOWN IN FOLLOWING FIGURE)



- 3. TAPE AND REEL SPECIFICATION IS AS PER EIA-481.
- 4. TAPE AND REEL QUANTITY : 600 PCS/ REEL.
- 5. THE TAPE IS TREATED FOR ANTI-STATIC.

785260011	28.50	477995127
785260001	30.70	887962916
ASSEMBLY P/N	DIM (B0)	PACKAGING P/N

SEE SHEET 1 EC NO: S2012-0960 DRWN: JZENG CHKD: JTAN02 APPR: KHLIM	2012/07/31 2012/08/27 2012/09/05	DESCRIPTION QUALITY SYMBOLS $F_A=0$ $F_G=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
				mm	INCH	DRAWN BY CGOH	DATE 2009/07/17	TITLE SIM CARD CONNECTOR PUSH PUSH TYPE HEIGHT 1.5MM				
			4 PLACES	± ---	± ---	CHECKED BY JTAN02	DATE 2009/08/17	MOLEX INCORPORATED				
			3 PLACES	± ---	± ---	APPROVED BY BOKOK	DATE 2010/11/11	DOCUMENT NO. SD-78526-001				
2 PLACES	± 0.25	± ---	ANGULAR ± 3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SHEET NO. 3 OF 3			
1 PLACE	± ---	± ---	MATERIAL NO.		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

9 8 7 6 5 4 3 2 1